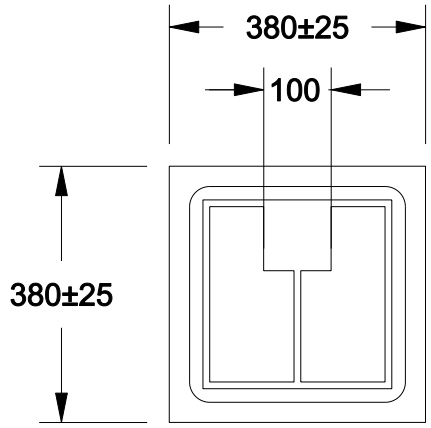
EO-UV375-1515-E1

EPIGAP OSA

InGaN LED Chip

- Metal reflector type
- Top emitting design
- N-Side up

- Both electrodes: Au alloy
- Suitable for Epoxy bonding



Chip size:	380±25µm x 380µm ±25µm
Chip thickness:	150µm ± 25µm
N-Pad:	100µm ± 10µm

Typical Electro-Optical Characteristics

Measurement conditions $T_{ambient}$ = 23 °C; t_{test} ≤ 60 ms

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Emitting Color	Ultraviolet					
Forward Voltage	V_f	I_f = 20 mA		3.30	3.80	V
Peak Wavelength	λ_P	I_f = 20 mA	370	375	380	nm
FWHM	$\Delta\lambda$	I_f = 20 mA		10		nm
Radiant Power (1)	I_e	I_f = 20 mA		23		mW
Reverse Current	I_R	U_R = 5V			2	µA

(1) Measured with EPIGAP OSA Equipment on bare die

Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Forward Current	$I_{f, max}$		30	mA
Reverse Voltage	U_R		5	V
Junction Temperature	T_J		115	°C
Operating Temperature	T_{op}	-40	85	°C
Storage Temperature	T_{St}	-20	65	°C

Maximum ratings are package dependent.

The specification above is showing general parameters. Custom binnings are welcome, please contact us for bespoke specifications.

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Notice

The information describes the type of component and shall not consider as assured characteristics. Terms of delivery and rights to change reserved. Due to technical requirements, components may contain dangerous substances.

It is the responsibility of the customer to evaluate and ensure that the use of the products in their specific applications complies with relevant safety standards and regulations. Customers must assess the exposure conditions within their systems and ensure that appropriate measures are taken to prevent exceeding the permissible exposure limits outlined in IEC 62471. EPIGAP OSA Photonics GmbH does not assume liability for any non-compliance arising from the integration or usage of LEDs in customer systems.

Parameters can vary in different applications. The customer must validate all operating parameters for each application. EPIGAP OSA Photonics GmbH does not have the responsibility for the reliability and the degradation behavior of products made with EPIGAP OSA Photonics GmbH diodes as they depend not only on the product itself but also on the operation, manufacturing or design of the final products. The customer is responsible to ensure the long-term stability of the product according to their requirements. If components are used in toys or, life support systems, EPIGAP OSA Photonics GmbH must expressly authorize the use of the components prior to incorporating them into the customer's systems!

Packaging: EPIGAP OSA Photonics GmbH uses recyclable packages.

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